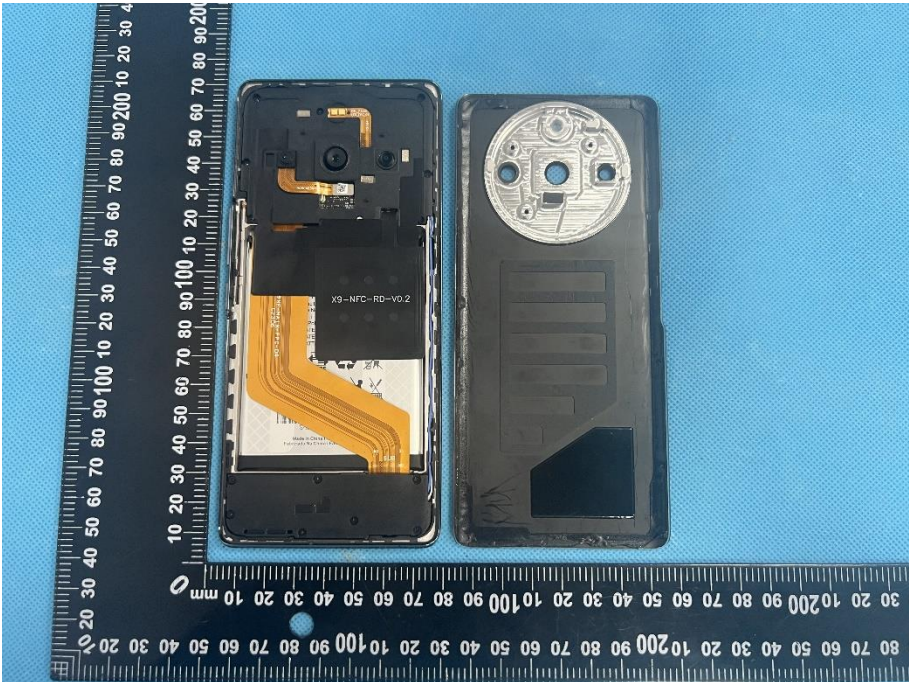
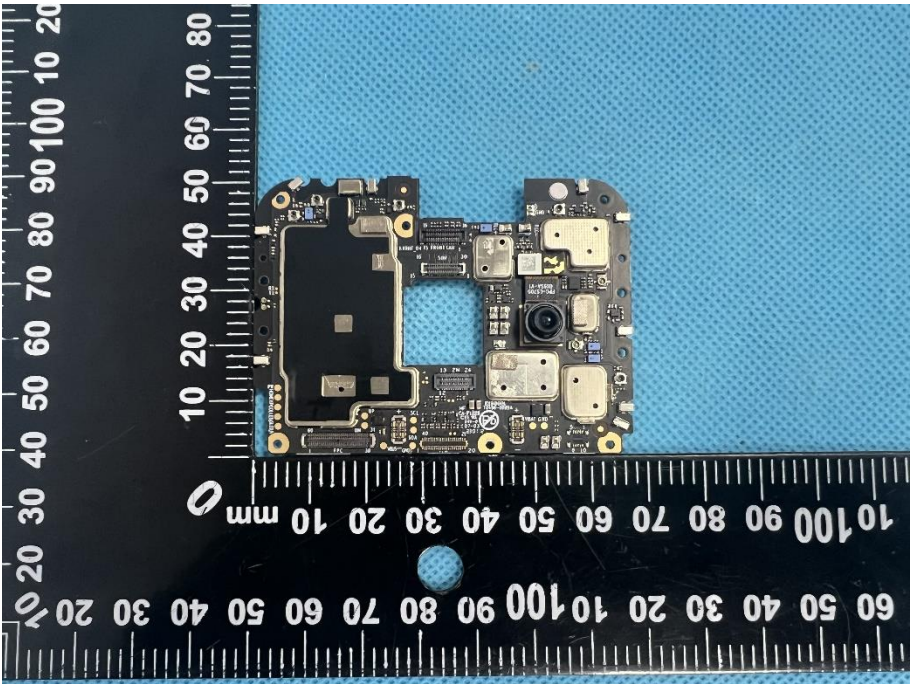
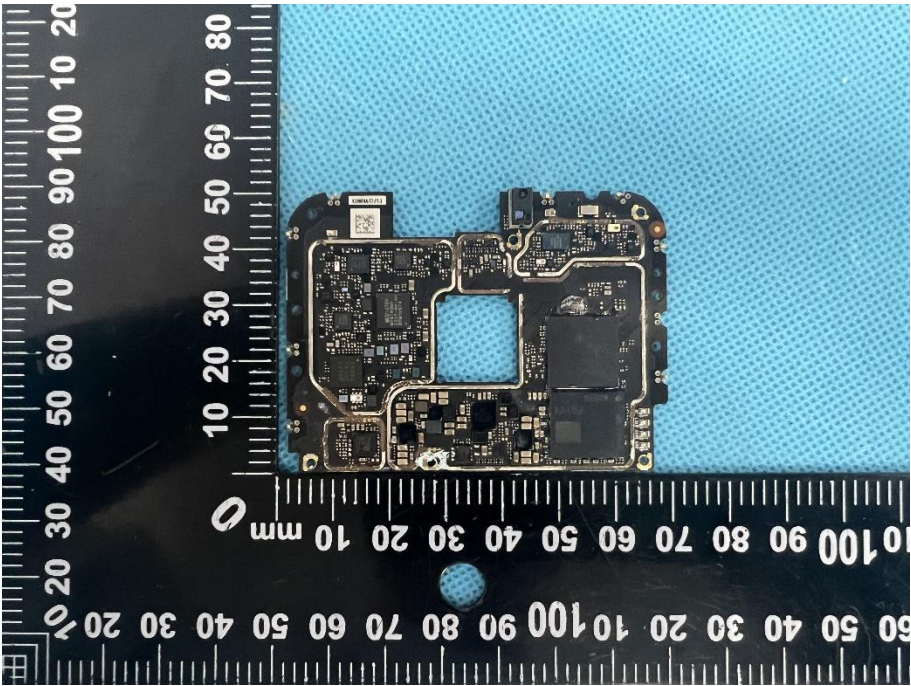
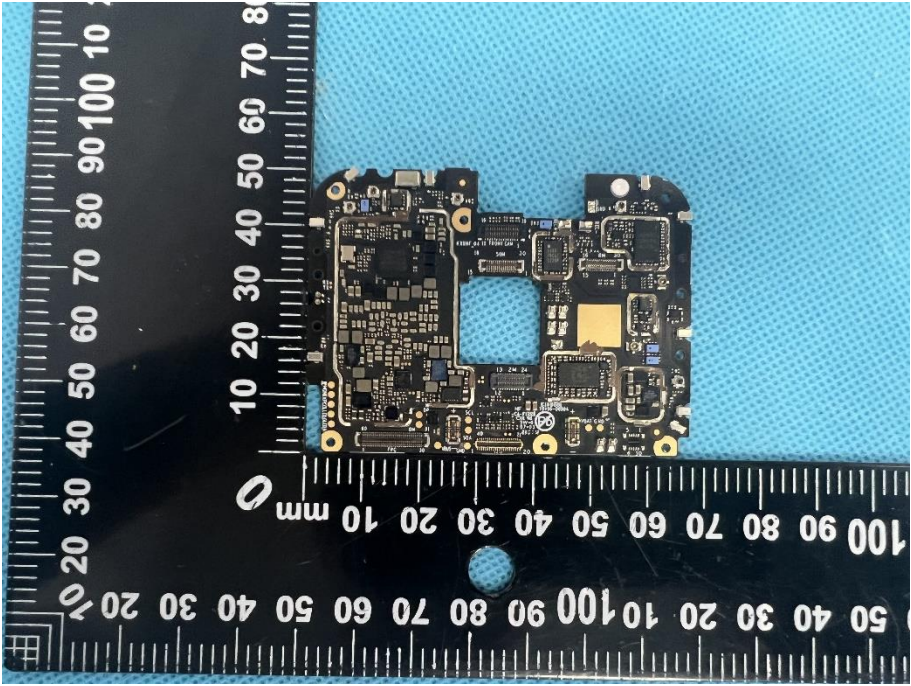
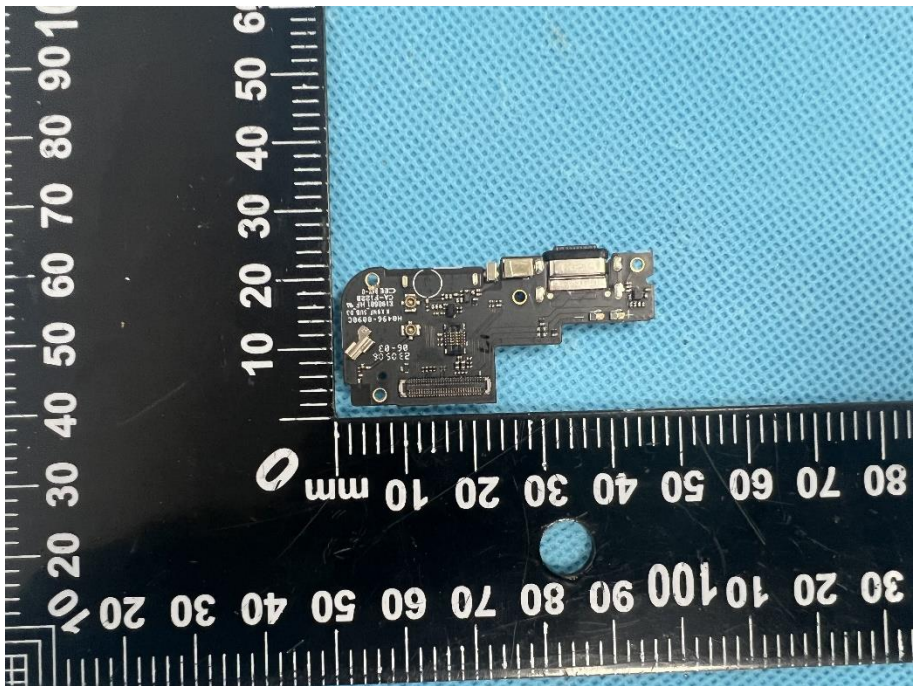
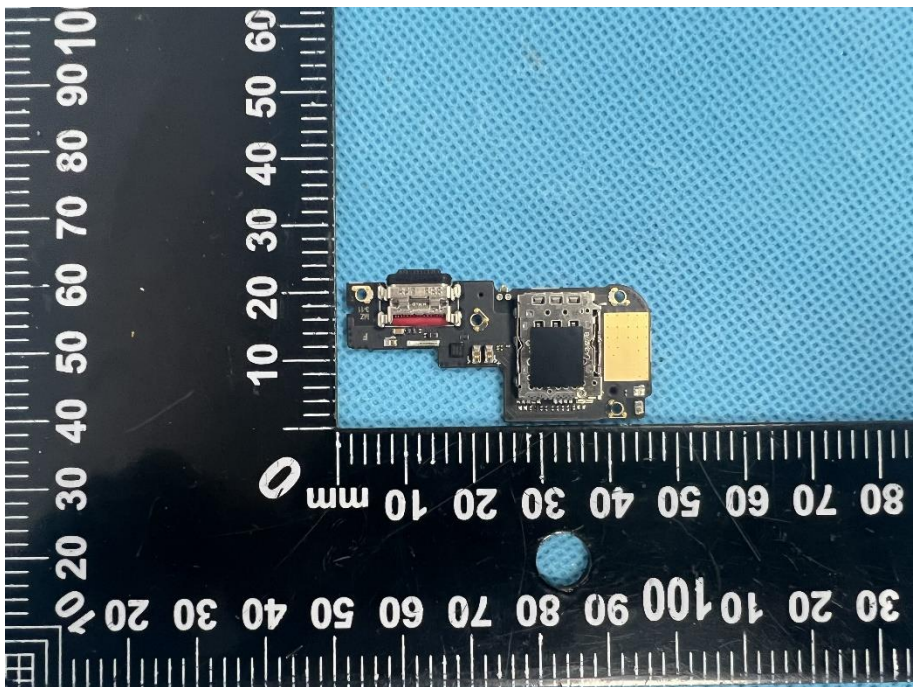


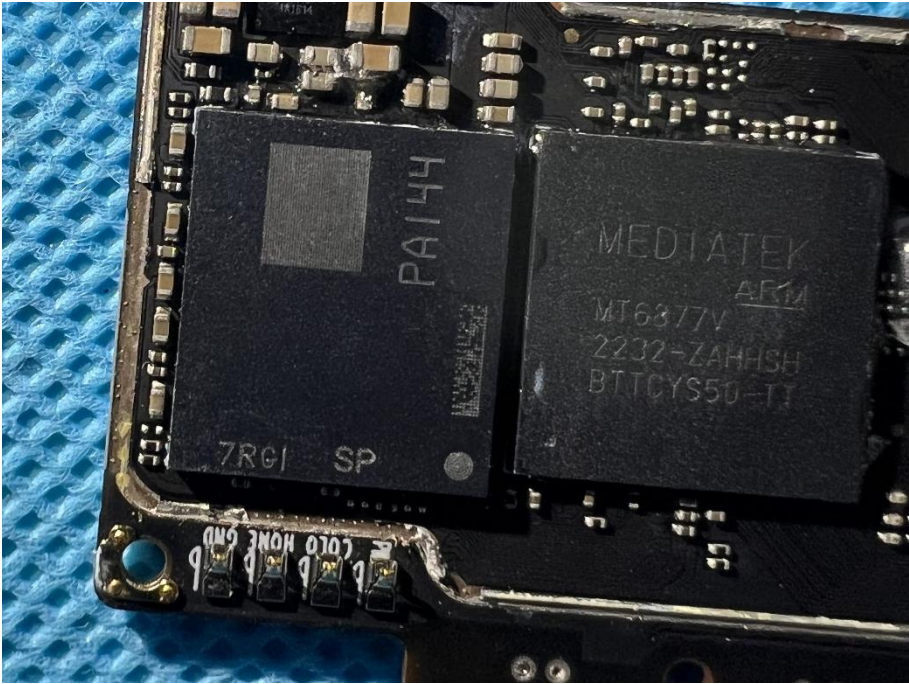
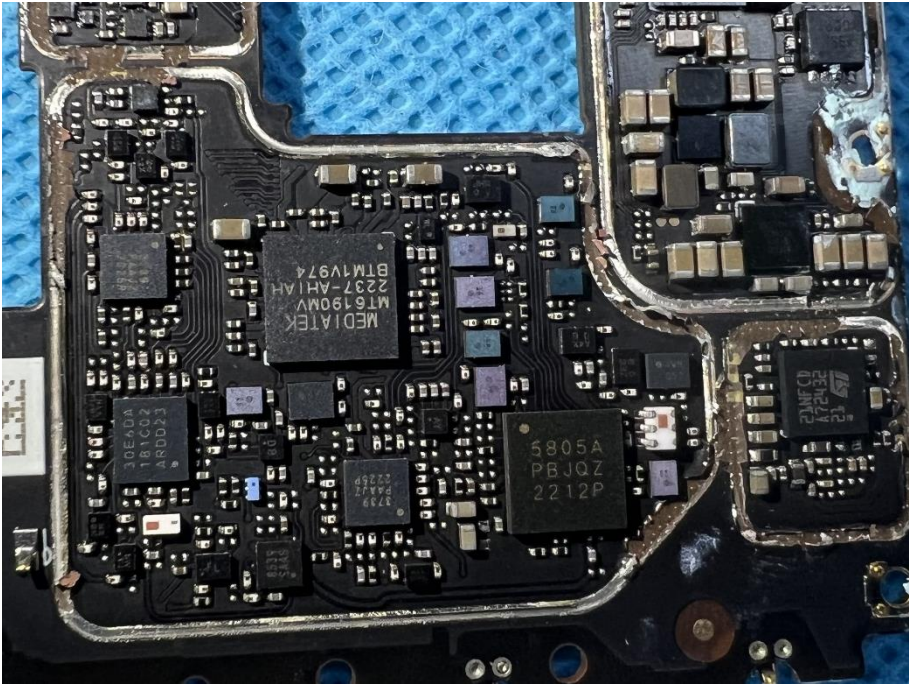
EXHIBIT 3 - EUT INTERNAL PHOTOGRAPHS

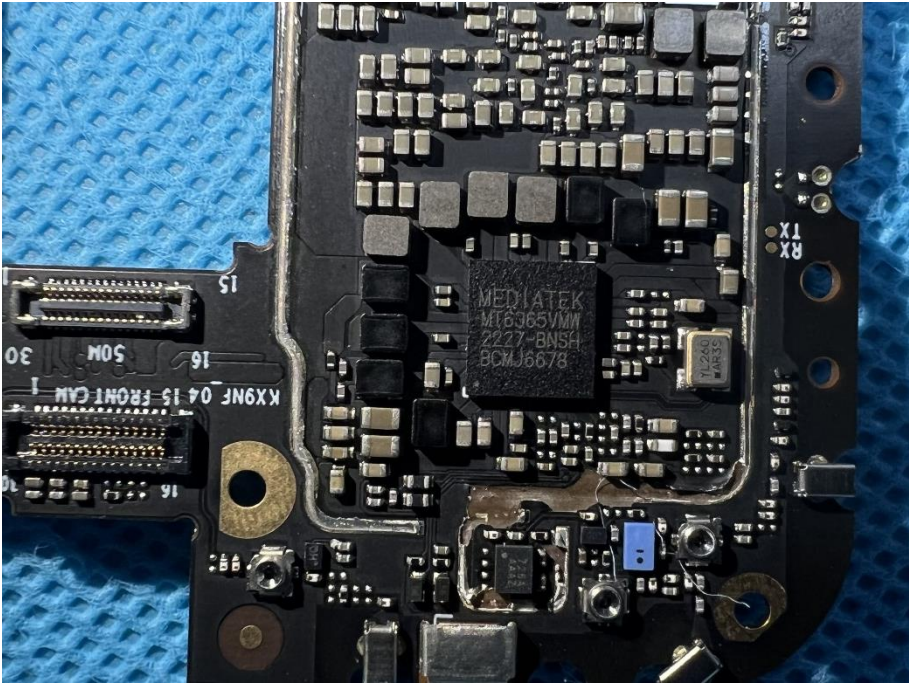
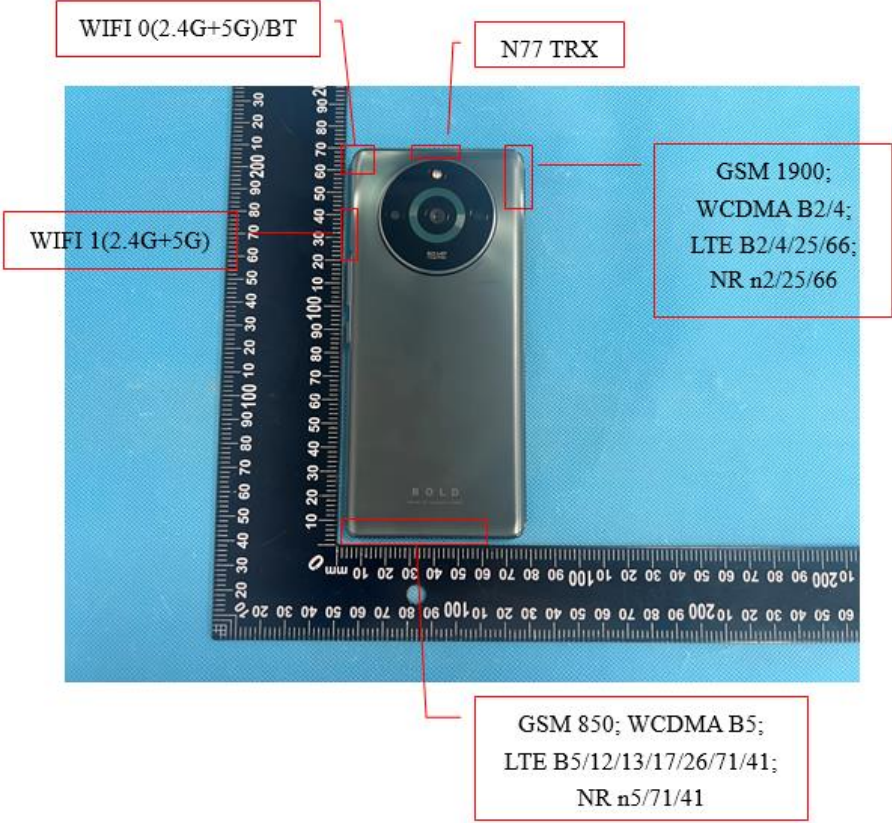
EUT Housing and Board View 1	 A photograph showing the internal components of a mobile phone, specifically the housing and board. The components are laid out on a blue surface next to a black ruler with white markings. The ruler is oriented vertically on the left and horizontally at the bottom. The housing is a black plastic frame. The board is a silver-colored printed circuit board (PCB) with various components, including a large orange flex cable, a camera lens, and a circular component. The text "X9-NFC-RD-V0.2" is visible on the board.
EUT Housing and Board View 2	 A photograph showing the internal components of a mobile phone, specifically the housing and board. The components are laid out on a blue surface next to a black ruler with white markings. The ruler is oriented vertically on the left and horizontally at the bottom. The housing is a black plastic frame. The board is a silver-colored printed circuit board (PCB) with various components, including a large orange flex cable, a camera lens, and a circular component. The text "LD 44700P" is visible on the board.

Solder Board-Component View 1	 A photograph of a small, rectangular electronic component, likely a camera module, resting on a blue textured surface. The component is positioned between two rulers. The ruler on the left is marked in millimeters from 0 to 100, and the ruler on the right is marked in millimeters from 0 to 100. The component is oriented horizontally, with its longer side parallel to the rulers. It features a central lens area, various electronic components, and a small label with the text "WALTEK" and "WTX23X05095991W001/002/003/004/005/006/007/008/009/010/011".
--	--

Solder Board-Component View 3	 A photograph of a complex printed circuit board (PCB) assembly, likely a mobile phone motherboard, showing various electronic components such as chips, capacitors, and connectors. The board is positioned against a blue background with a white grid pattern. A black ruler with white markings is placed horizontally below the board, showing measurements in millimeters. The ruler has markings from 0 to 100 mm on the top edge and 0 to 100 mm on the bottom edge.
Solder Board-Component View 4	 A photograph of the same PCB assembly from a different perspective, showing the underside or a different side of the board. The board is positioned against a blue background with a white grid pattern. A black ruler with white markings is placed horizontally below the board, showing measurements in millimeters. The ruler has markings from 0 to 100 mm on the top edge and 0 to 100 mm on the bottom edge.

Solder Board-Component View 5	 A photograph of a small electronic component, likely a solder board, placed on a blue textured surface. The component is positioned next to a black ruler with white markings. The ruler shows measurements in millimeters (0 to 100) and centimeters (0 to 10). The component is small and rectangular, with various electronic components and solder joints visible.
Solder Board-Component View 6	 A photograph of the same electronic component from a different angle (View 6). The component is placed on the same blue textured surface next to the same black ruler. This view shows the underside of the component, revealing a large square chip, various solder joints, and other electronic components.

Solder Board-Component View 7	
Solder Board-Component View 8	

Solder Board-Component View 9	 A photograph of a mobile phone's internal circuit board, showing various components and solder joints. A central chip is labeled 'MEDIATEK MT6365MM 2227-BNSH BCMJ6678'. Other labels include 'KXNF 04 15 FRONT CAM', 'MOS', and '16'. The board is populated with numerous small surface-mount components and larger integrated circuits.
Antenna View 1	 A photograph of a smartphone (Huawei P30) with a ruler placed next to it for scale. Red boxes and lines identify specific antenna locations and their supported frequency bands: WIFI 0(2.4G+5G)/BT: Located at the top left of the phone. N77 TRX: Located at the top center of the phone. WIFI 1(2.4G+5G): Located at the top right of the phone. GSM 1900; WCDMA B2/4; LTE B2/4/25/66; NR n2/25/66: Located on the right side of the phone. GSM 850; WCDMA B5; LTE B5/12/13/17/26/71/41; NR n5/71/41: Located at the bottom of the phone.

